

BB02-YF

CUSTOMER PRODUCT SPECIFICATION SHEET



BB02-YF:- 1.00mm x 1.00mm (0.039" x 0.039") PIN HEADER, DUAL ROW, STRAIGHT, SMT TYPE, 04 TO 80 CONTACTS

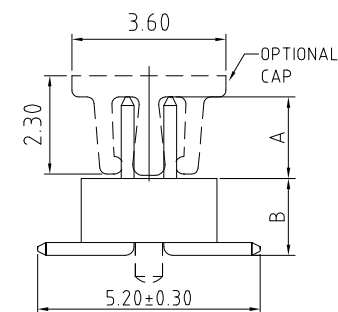
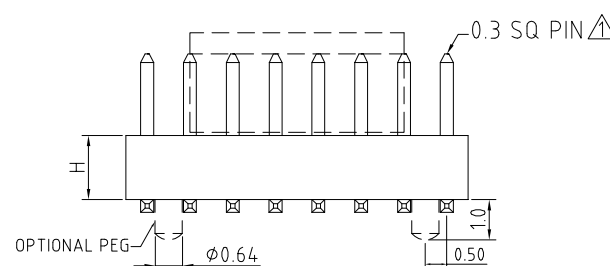
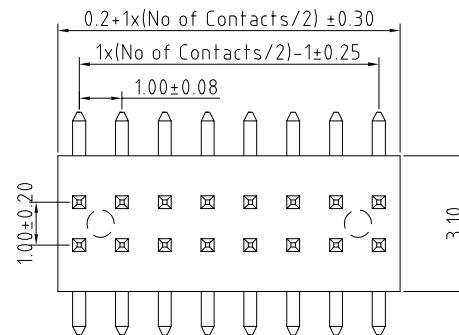
SPECIFICATIONS

CURRENT RATING: 1AMP  
 INSULATOR RESISTANCE: 500 MEGOHMS MIN.  
 DIELECTRIC WITHSTANDING: AC 300 V  
 CONTACT RESISTANCE: 20m OHMS MAX.  
 OPERATING TEMPERATURE: -40°C TO +105°C  
 CONTACT MATERIAL: PHOSPHOR BRONZE  
 INSULATOR MATERIAL: THERMOPLASTIC, UL 94V-0  
 STANDARD:LCP  
 PLATING: GOLD OR TIN OVER 30-50U" NICKEL  
 SOLDERABILITY IR REFLOW: 280°C FOR 10 SEC  
 MANUAL SOLDER: 380°C FOR 3-5 SEC

MATES WITH: - BB02-WA

NOTES:

1. PARTS WITH SMALL PIN NUMBERS WILL BE PACKED IN BOX INSTEAD OF TUBE, CONTACT GRADCONN FOR MORE INFORMATION.



HOW TO ORDER



NO. OF CONTACTS:  
 04 to 80  
 (MIN. PIN# 06 FOR W/PEG VERSION.)

CONTACT PLATING OPTIONS:  
 K = GOLD FLASH (STANDARD)  
 P = 10U" GOLD OVERALL  
 Q = 15U" GOLD OVERALL  
 R = 30U" GOLD OVERALL  
 T = BRIGHT TIN  
 M = MATT TIN

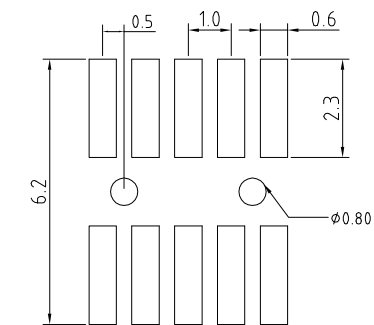
LOCATING PEG OPTIONS:  
 A = WITH PEG  
 B = WITHOUT PEG

PACKAGING OPTIONS:  
 3 = TUBE or BOX  
 5 = TUBE or BOX + CAP  
 6 = TAPE & REEL  
 8 = TAPE & REEL + CAP  
 (SEE NOTE 1)

PIN LENGTH A (1/10mm)  
 PLEASE SPECIFY PIN LENGTH REQUIRED  
 I.E. 2.5mm = 25  
 TOL. ±0.25mm

INSULATOR HEIGHT 'H'  
 0: H = 1.5mm  
 1: H = 1.0mm  
 STANDARD = 0

PIN LENGTH B (1/10mm)  
 PLEASE SPECIFY PIN LENGTH REQUIRED  
 I.E. 2.5mm = 25  
 TOL. ±0.25mm  
 MIN. B =1.9mm if H =1.5mm  
 MIN. B =1.4mm if H =1.0mm



RECOMMENDED PCB SMT LAYOUT

|      |                |   |
|------|----------------|---|
| REV. | DATE & DRN     | DESCRIPTION                                 |
| 10   | 26/06/05-NYW   | RELEASE                                     |
| 11   | 12/07/05-NYW   | ADD LOCATING PEG OPTION                     |
| 12   | 08/08/06 - CHC | AMEND PIN DIMENSION                         |
| 13   | 12/12/06 - NYW | DRAWING MODIFICATION                        |
| 14   | 17/07/07 - CHC | AMEND MIN. PIN# TO 04.                      |
| 15   | 09/04/08 - NYW | AMEND INSULATOR OPTION PLATING MODIFICATION |
| 16   | 23/07/08 - NYW | CHANGE PLATING OPTIONS.                     |
| 17   | 11/08/08 - CHC | ADD MIN. DIMENSION OF "B".                  |
| 18   | 26/11/08 - CHC | DRAWING MODIFICATION                        |
| 19   | 24/12/08 - NYW | DRAWING MODIFICATION                        |
| 20   | 08/02/14 - NYW | AMEND PIN MATERIAL                          |
| 21   | 25/02/15 - NYW | AMEND PIN MATERIAL                          |
| 22   | 21/12/23 - NYW | UPDATE PACKAGING OPTIONS                    |

|        |           |
|--------|-----------|
| Scale: | 8:1       |
| Drawn: | NYW       |
| App'd: | XXX       |
| Date:  | 21DEC '23 |

|             |            |
|-------------|------------|
| THIRD ANGLE |            |
| Title:      | PIN HEADER |
| Revision:   | 2.2        |

|                      |            |
|----------------------|------------|
| Unstated Tolerances: | X. ± 0.30  |
|                      | X ± 0.25   |
|                      | XX ± 0.15  |
|                      | XXX ± 0.10 |

|              |          |
|--------------|----------|
| Material     | SEE NOTE |
| NOT TO SCALE |          |
| Unit:        | mm       |

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|                 |             |
|-----------------|-------------|
| Type            | BB02-YF     |
| Drawing Number: | BB02-YF     |
| Sheet           | 1 of 1      |
| Drawing         | © E and O E |